

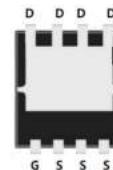


## Features

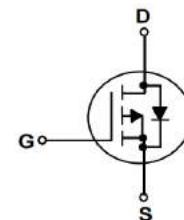
- P-Channel
- High density cell design for ultra low  $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation

$V_{DS}$	-20	V
$R_{DS(on),TYP}$ @ $V_{GS}=-4.5$ V	2.2	mΩ
$R_{DS(on),TYP}$ @ $V_{GS}=-2.5$ V	3.3	mΩ
$I_D$	-80	A

DNF5x6



Part ID	Package Type	Marking	Packing
ZT020P02G	DFN5x6	ZT020P02G	5000pcs/reel



**Absolute Maximum Ratings  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Symbol	Parameter	Rating	Unit	
<b>Common Ratings (<math>T_c=25^\circ\text{C}</math> Unless Otherwise Noted)</b>				
$V_{GS}$	Gate-Source Voltage	$\pm 10$	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-20	V	
$T_J$	Maximum Junction Temperature	150	°C	
$T_{STG}$	Storage Temperature Range	-55 to 150	°C	
$I_{DM}$	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_c=25^\circ\text{C}$	-320	A
<b>Mounted on Large Heat Sink</b>				
$I_D$	Drain Current-Continuous	$T_c=25^\circ\text{C}$	-80	A
		$T_c=100^\circ\text{C}$	-49.5	A
$P_D$	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	130	W
	Derating factor		1.04	W/ °C
$R_{TJC}$	Thermal Resistance-Junction to Case (Note 2)		0.96	°C/W



**Electrical Characteristics  $T_J=25$  unless otherwise noted**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ <math>T_J=25^\circ\text{C}</math> (unless otherwise stated)</b>						
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-20	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS}=-20\text{V}, V_{GS}=0\text{V}$	--	--	-1	$\mu\text{A}$
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{GS}=\pm 10\text{V}, V_{DS}=0\text{V}$	--	--	$\pm 100$	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-0.4	-0.6	-1.0	V
R <sub>D(on)</sub>	Drain-Source On-State Resistance	$V_{GS}=-4.5\text{V}, I_D=-20\text{A}$	--	2.2	3.3	$\text{m}\Omega$
R <sub>D(on)</sub>	Drain-Source On-State Resistance	$V_{GS}=-2.5\text{V}, I_D=-20\text{A}$	--	3.3	4.5	$\text{m}\Omega$
g <sub>FS</sub>	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-20\text{A}$	100	--	--	S

**Dynamic Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise stated)** (Note 4)

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V, f=1MHz	--	7990	--	pF
C <sub>oss</sub>	Output Capacitance		--	890	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	760	--	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DD</sub> =-10V, I <sub>D</sub> =-20A, V <sub>GS</sub> =-10V	--	153	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	6.1	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	21	--	nC

**Switching Characteristics** (Note 4)

T <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =-10V, R <sub>L</sub> =0.5Ω, R <sub>G</sub> =6Ω, V <sub>GS</sub> =-10V	--	13	--	ns
T <sub>r</sub>	Turn-on Rise Time		--	12	--	ns
T <sub>d(off)</sub>	Turn-Off Delay Time		--	350	--	ns
T <sub>f</sub>	Turn-Off Fall Time		--	136	--	ns

**Source-Drain Diode Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise stated)**

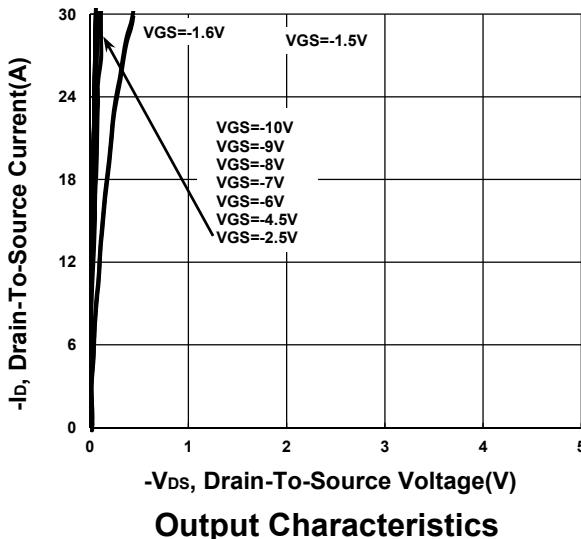
I <sub>SD</sub>	Source-Drain Current (Body Diode) (Note 2)		--	--	-80	A
V <sub>SD</sub>	Forward on voltage (Note 3)	I <sub>s</sub> =-20A, V <sub>GS</sub> =0V	--	--	-1.3	V
T <sub>rr</sub>	Reverse Recovery Time	T <sub>J</sub> =25, I <sub>F</sub> =-20A, V <sub>GS</sub> =0V di/dt=100A/μs	--	75	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	61	--	nC

Note :

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

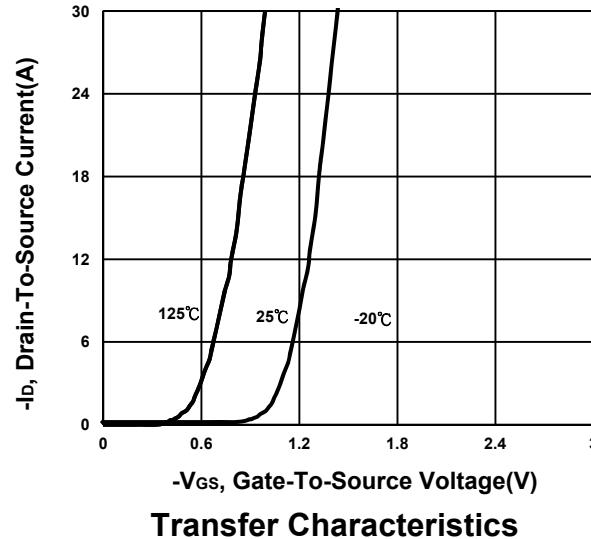


## Typical Electrical And Thermal Characteristics (Curves)



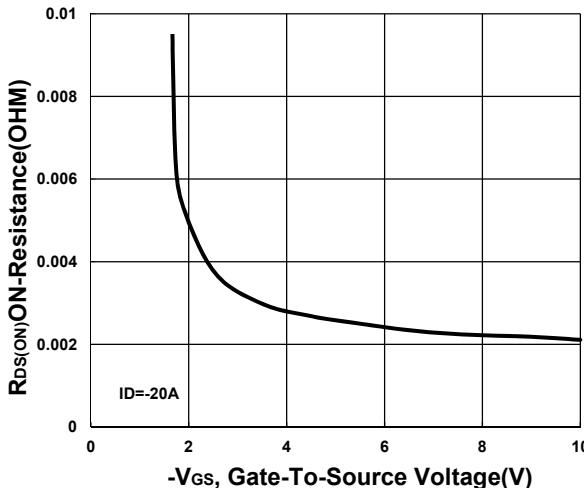
- $V_{DS}$ , Drain-To-Source Voltage(V)

Output Characteristics



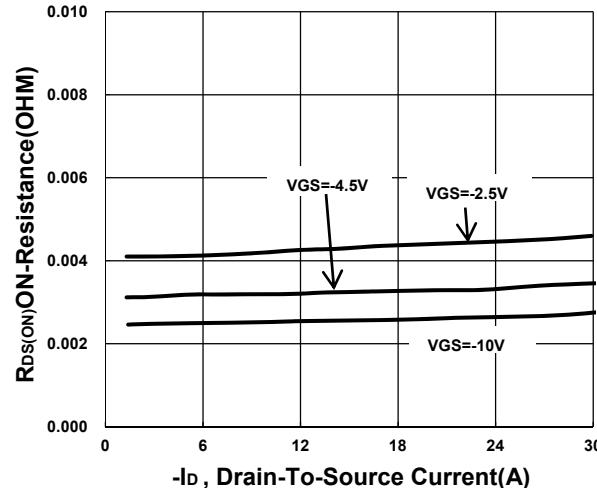
- $V_{GS}$ , Gate-To-Source Voltage(V)

Transfer Characteristics



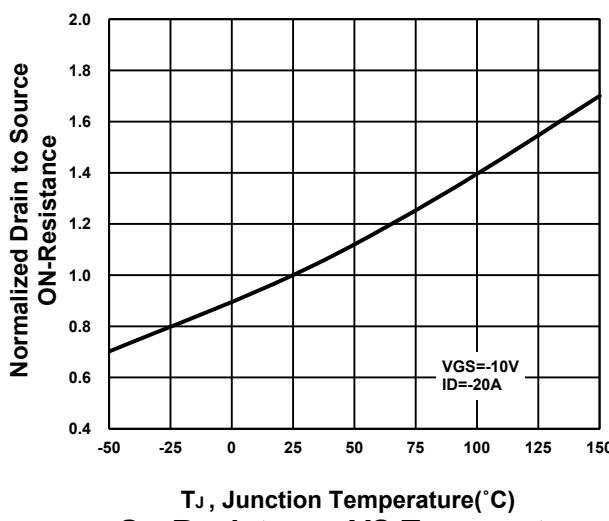
- $V_{GS}$ , Gate-To-Source Voltage(V)

On-Resistance VS Gate-To-Source



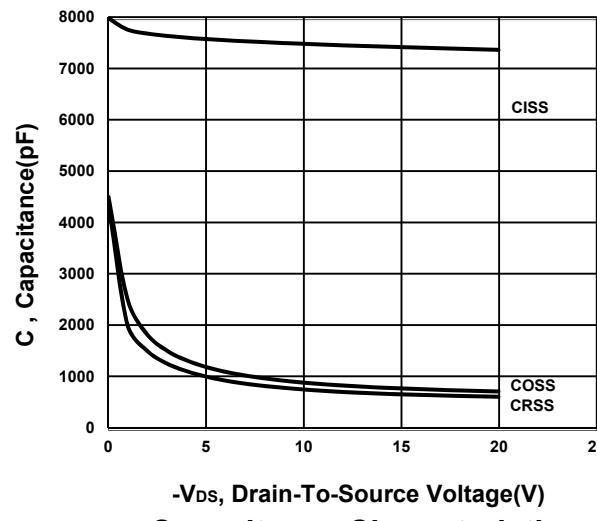
- $I_D$ , Drain-To-Source Current(A)

On-Resistance VS Drain Current



$T_J$ , Junction Temperature(°C)

On-Resistance VS Temperature

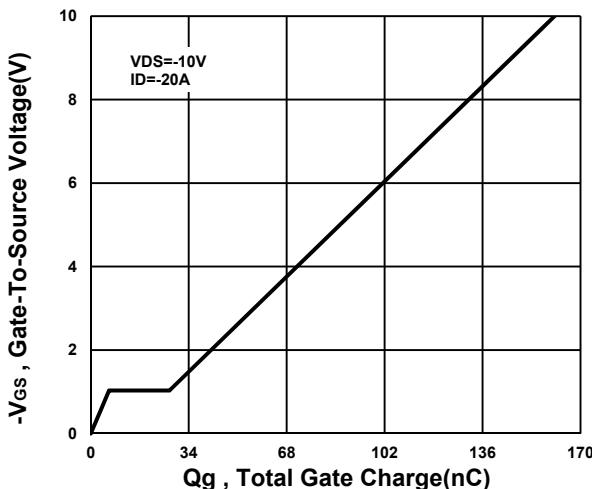


- $V_{DS}$ , Drain-To-Source Voltage(V)

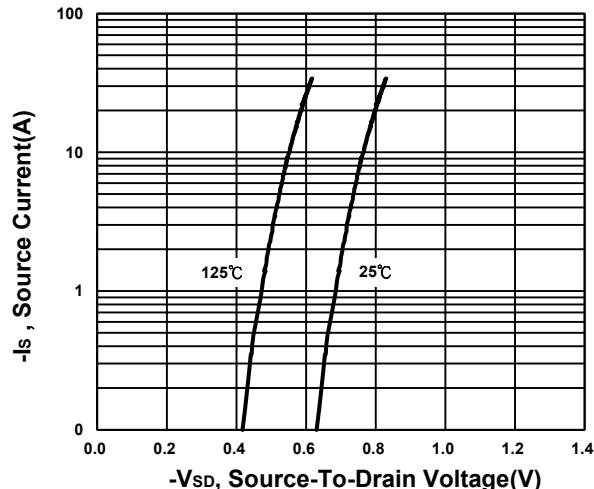
Capacitance Characteristic



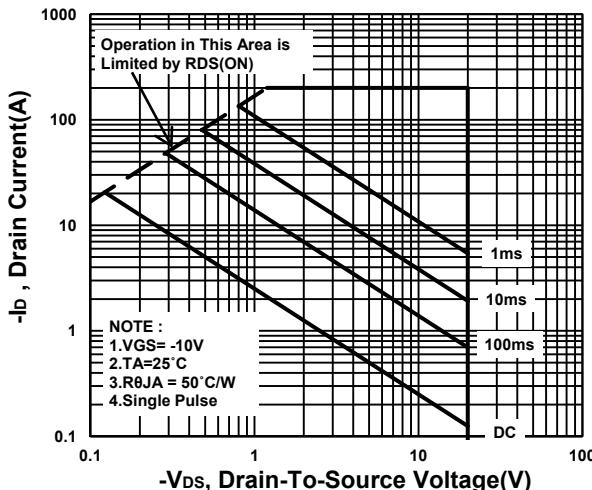
## Typical Electrical And Thermal Characteristics (Curves)



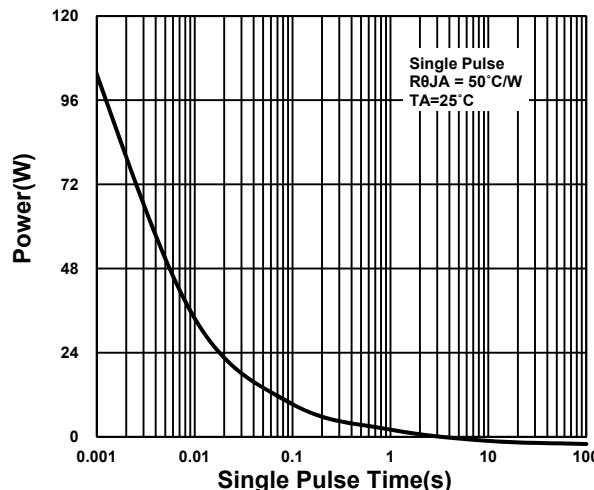
Gate charge Characteristics



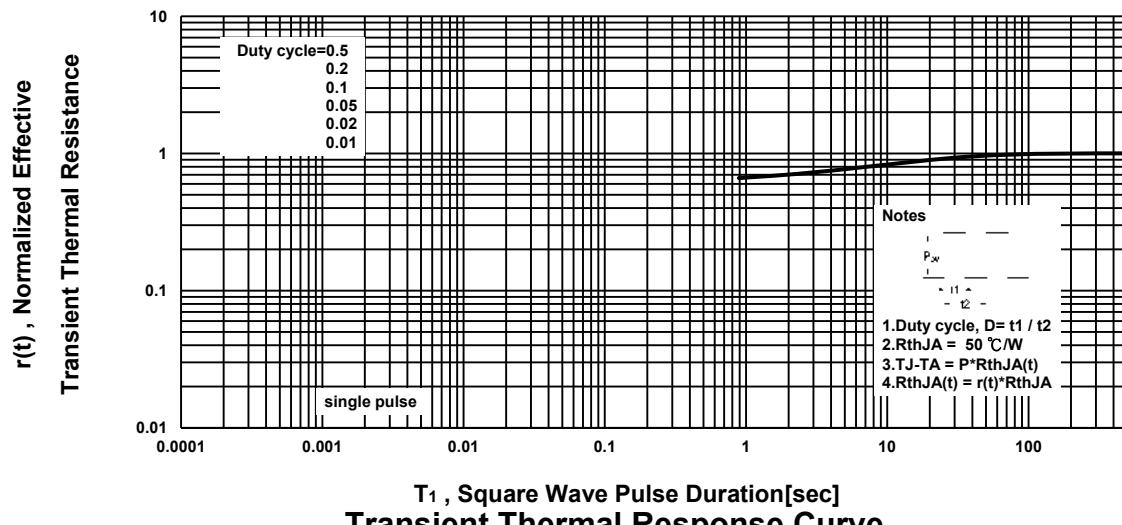
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation

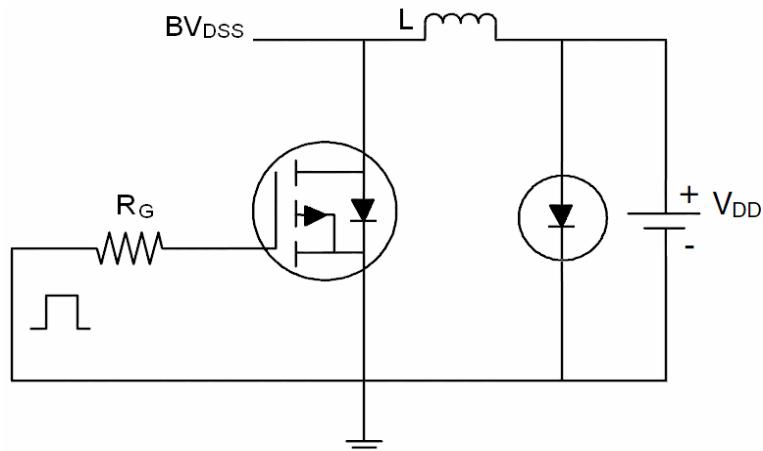


Transient Thermal Response Curve

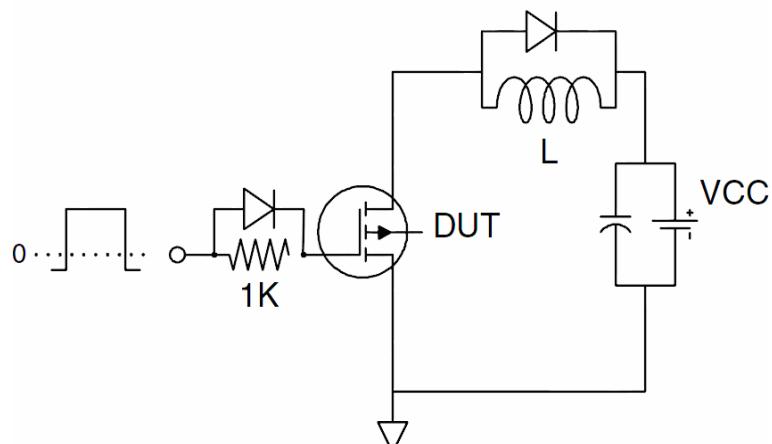


## Test Circuit

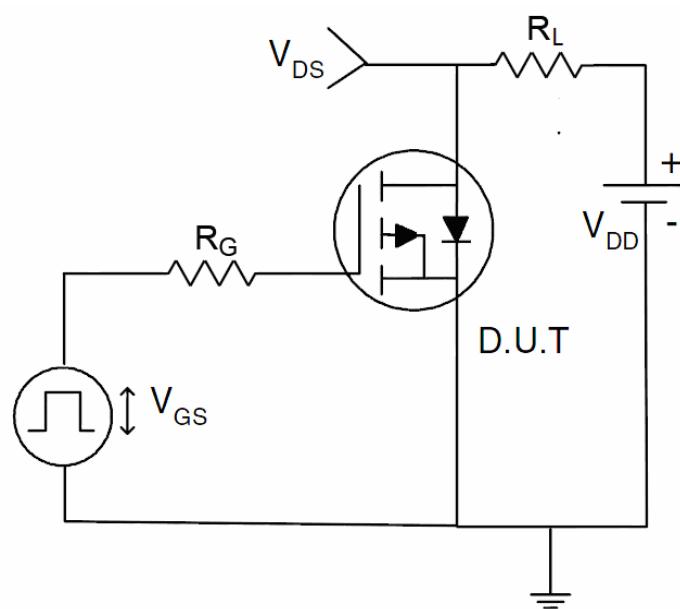
### 1) E<sub>AS</sub> Test Circuit



### 2) Gate Charge Test Circuit

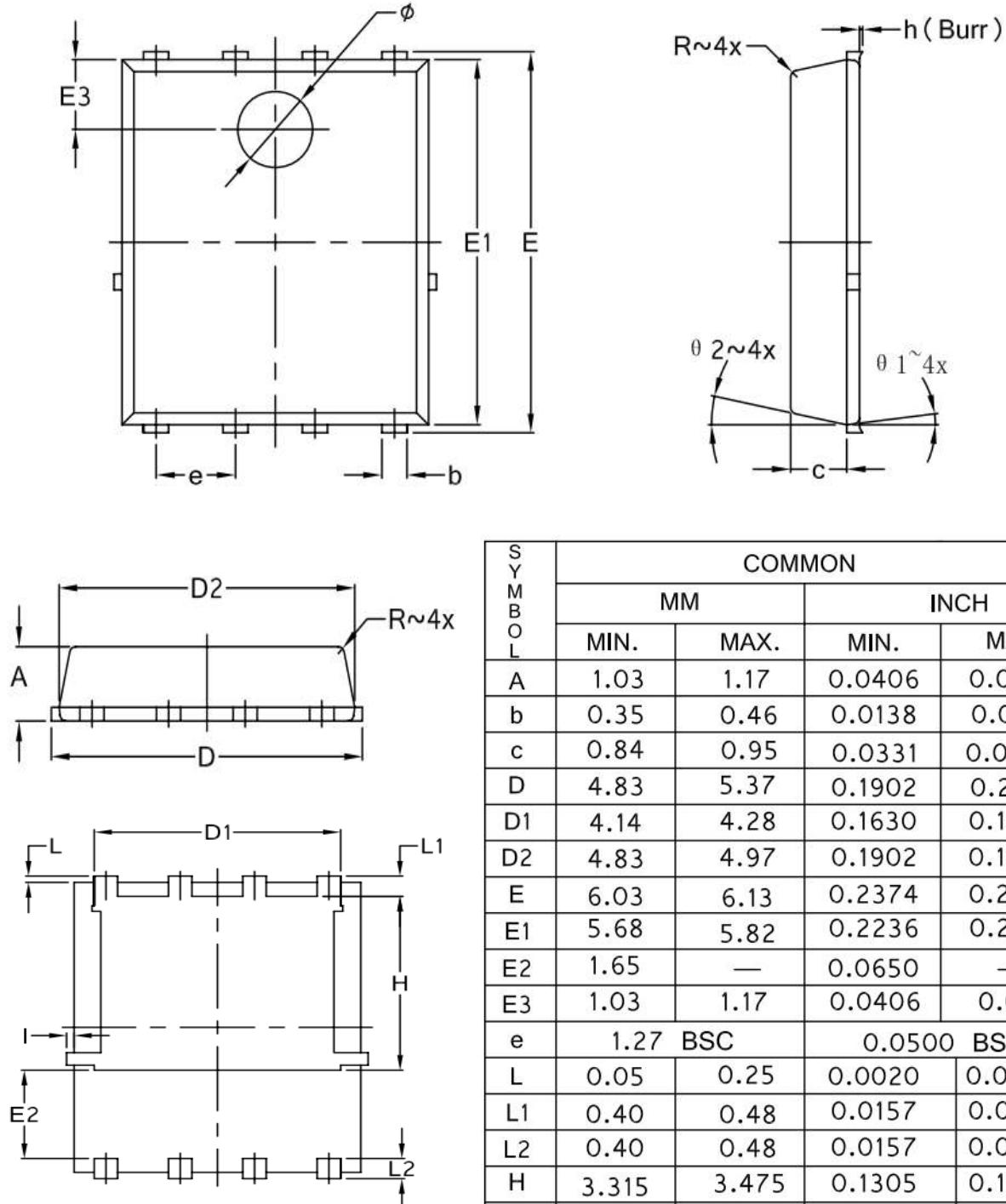


### 3) Switch Time Test Circuit





## DFN5x6-8L Package Information



SYMBOL	COMMON			
	MM		INCH	
	MIN.	MAX.	MIN.	MAX.
A	1.03	1.17	0.0406	0.0461
b	0.35	0.46	0.0138	0.0181
c	0.84	0.95	0.0331	0.0374
D	4.83	5.37	0.1902	0.2114
D1	4.14	4.28	0.1630	0.1685
D2	4.83	4.97	0.1902	0.1957
E	6.03	6.13	0.2374	0.2413
E1	5.68	5.82	0.2236	0.2291
E2	1.65	—	0.0650	—
E3	1.03	1.17	0.0406	0.0461
e	1.27	BSC	0.0500	BSC
L	0.05	0.25	0.0020	0.0098
L1	0.40	0.48	0.0157	0.0189
L2	0.40	0.48	0.0157	0.0189
H	3.315	3.475	0.1305	0.1368
I	—	0.16	—	0.0063
$\phi$	1.13	1.27	0.0445	0.0500
R	0.10		0.0039	
$\theta_1$	7° REF		7° REF	
$\theta_2$	12° REF		12° REF	
h	0.08 MAX		0.0031	

## Customer Service

Sales and Service:

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